M80C51FB
CHMOS SINGLE-CHIP 8-BIT MICROCONTROLLER

Military

M80C51FB — 3.5 MHz to 12 MHz, V_{CC} = 5V ±20%
M80C51FB-16 — 3.5 MHz to 16 MHz, V_{CC} = 5V ±20%

- **Three 16-Bit Timer/Counters**
- **Programmable Clock Out**
- **Programmable Counter Array with:**
  - **— High Speed Output,**
  - **— Compare/Capture,**
  - **— Pulse Width Modulator,**
  - **— Watchdog Timer capabilities**
- **Up/Down Timer/Counter**
- **256 Bytes of On-Chip Data RAM**
- **Boolean Processor**
- **ONCE (On-Circuit Emulation) Mode**
- **Available in 40-pin CERDIP and 44-pin Leadless Chip Carrier Packages**
- **Gull Wing and J-Lead Packages also Available**
- **32 Programmable I/O Lines**
- **7 Interrupt Sources**
- **Programmable Serial Channel with:**
  - **— Framing Error Detection**
  - **— Automatic Address Recognition**
- **TTL and CMOS Compatible Logic Levels**
- **64K External Program Memory Space**
- **64K External Data Memory Space**
- **MCS® 51 Microcontroller Fully Compatible Instruction Set**
- **Power Saving Idle and Power Down Modes**
- **Military Temperature Range: −55°C to +125°C (T_C)**

MEMORY ORGANIZATION

PROGRAM MEMORY: The M80C51FB can address up to 64K of program memory external to the chip.

DATA MEMORY: This microcontroller has a 256 x 8 on-chip RAM. In addition it can address up to 64K bytes of external data memory.

The Intel M80C51FB is a single-chip control-oriented microcontroller which is fabricated on Intel's reliable CHMOS III-E technology. Being a member of the family of MCS 51 microcontrollers, the M80C51FB uses the same powerful instruction set, has the same architecture, and is pin for pin compatible with the existing MCS 51 microcontroller family of products. The M80C51FB is an enhanced version of the M80C51. Its added features make it an even more powerful microcontroller for applications that require Pulse Width Modulation, High Speed I/O, and up/down counting capabilities such as motor control or fin actuation. It also has a more versatile serial channel that facilitates multi-processor communications.

October 1994 **Order Number: 271172-002**

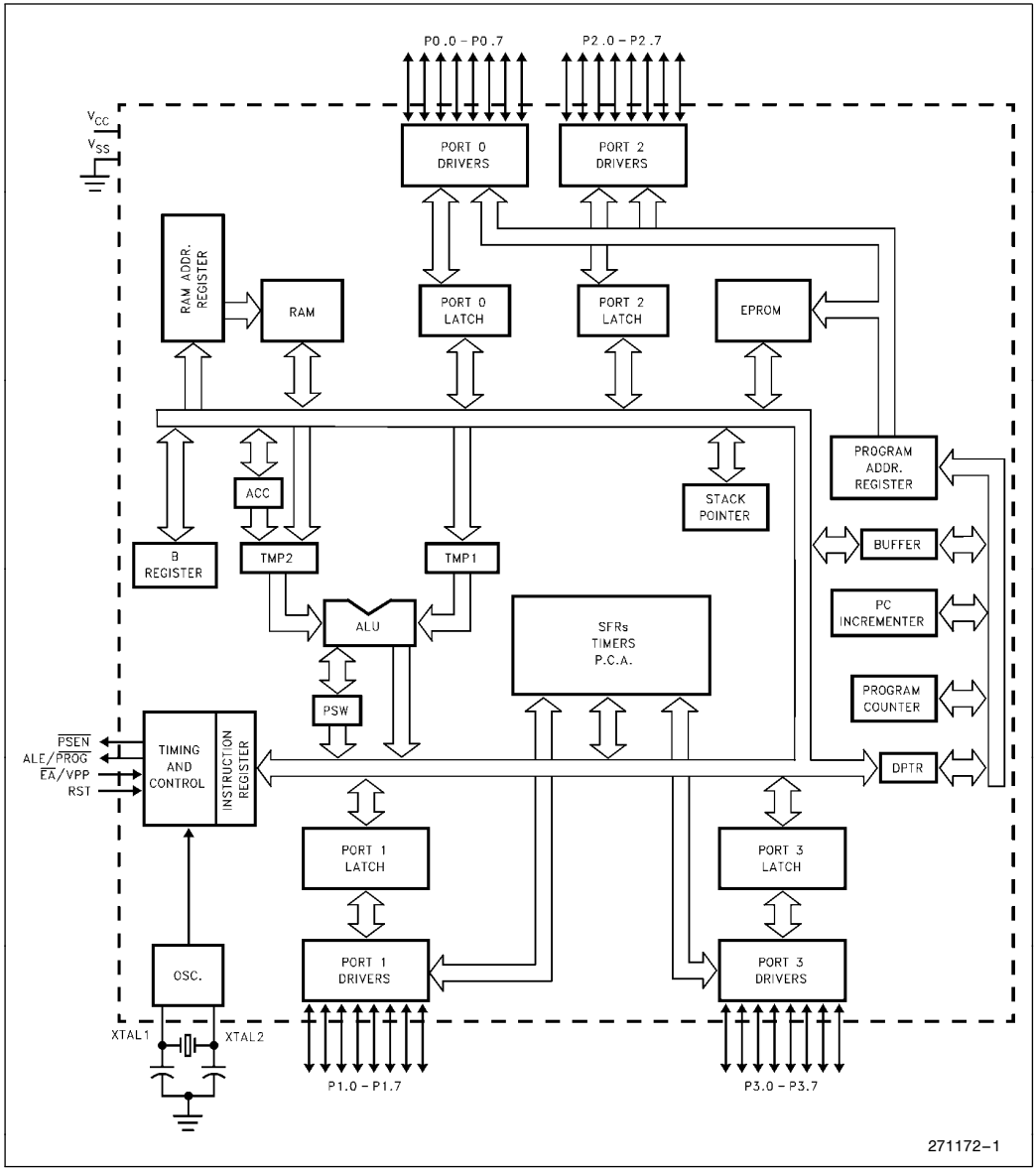


Figure 1. M80C51FB Block Diagram

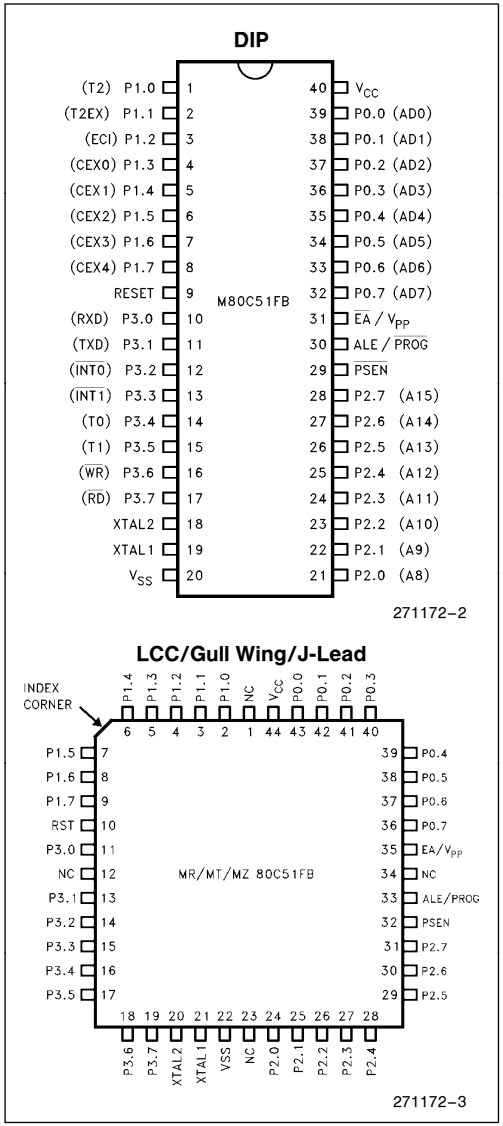


Figure 2. M80C51FB Pin Connections

PIN DESCRIPTIONS

V_{CC}: Supply voltage.

V_{SS}: Circuit ground.

Port 0: Port 0 is an 8-bit, open drain, bidirectional I/O port. As an output port each pin can sink several LS TTL inputs. Port 0 pins that have 1's written to them float, and in that state can be used as high-impedance inputs.

Port 0 is also the multiplexed low-order address and data bus during accesses to external Program and Data Memory. In this application it uses strong internal pullups when emitting1's, and can source and sink several LS TTL inputs.

Port 1: Port 1 is an 8-bit bidirectional I/O port with internal pullups. The Port 1 output buffers can drive LS TTL inputs. Port 1 pins that have 1's written to them are pulled high by the internal pullups, and in that state can be used as inputs. As inputs, Port 1 pins that are externally being pulled low will source current (I_{IL}, on the data sheet) because of the internal pullups.

In addition, Port 1 serves the functions of the following special features of the M80C51FB:

Port Pin	Alternate Function
P1.0	T2 (External Count Input to Timer/ Counter 2)
P1.1	T2EX (Timer/Counter 2 Capture/ Reload Trigger and Direction Control)
P1.2	ECI (External Count Input to the PCA)
P1.3	CEX0 (External I/O for Compare/ Capture Module 0)
P1.4	CEX1 (External I/O for Compare/ Capture Module 1)
P1.5	CEX2 (External I/O for Compare/ Capture Module 2)
P1.6	CEX3 (External I/O for Compare/ Capture Module 3)
P1.7	CEX4 (External I/O for Compare/ Capture Module 4)

Port 2: Port 2 is an 8-bit bidirectional I/O port with internal pullups. The Port 2 output buffers can drive LS TTL inputs. Port 2 pins that have 1's written to them are pulled high by the internal pullups, and in that state can be used as inputs. As inputs, Port 2 pins that are externally being pulled low will source current (I_{IL}, on the data sheet) because of the internal pullups.

Port 2 emits the high-order address byte during fetches from external Program Memory and during accesses to external Data Memory that use 16-bit addresses (MOVX @DPTR). In this application it uses strong internal pullups when emitting 1's. During accesses to external Data Memory that use 8-bit addresses (MOVX @Ri), Port 2 emits the contents of the P2 Special Function Register.

Port 3: Port 3 is an 8-bit bidirectional I/O port with internal pullups. The Port 3 output buffers can drive LS TTL inputs. Port 3 pins that have 1's written to them are pulled high by the internal pullups, and in that state can be used as inputs. As inputs, Port 3 pins that are externally being pulled low will source current (I_{IL}, on the data sheet) because of the pullups.

Port 3 also serves the functions of various special features of the M8051 Family, as listed below:

Port Pin	Alternate Function
P3.0	RXD (serial input port)
P3.1	TXD (serial output port)
P3.2	$\overline{INT0}$ (external interrupt 0)
P3.3	$\overline{INT1}$ (external interrupt 1)
P3.4	T0 (Timer 0 external input)
P3.5	T1 (Timer 1 external input)
P3.6	$\overline{WR}$ (external data memory write strobe)
P3.7	$\overline{RD}$ (external data memory read strobe)

RST: Reset input. A high on this pin for two machine cycles while the oscillator is running resets the device. An internal pulldown resistor permits a power-on reset with only a capacitor connected to V_{CC}.

ALE: Address Latch Enable output pulse for latching the low byte of the address during accesses to external memory.

In normal operation ALE is emitted at a constant rate of 1/6 the oscillator frequency, and may be used for external timing or clocking purposes. Note, however, that one ALE pulse is skipped during each access to external Data Memory.

$\overline{PSEN}$: Program Store Enable is the read strobe to external Program Memory.

When the M80C51FB is executing code from external Program Memory, $\overline{PSEN}$ is activated twice each machine cycle, except that two $\overline{PSEN}$ activations are skipped during each access to external Data Memory.

$\overline{EA}$: External Access enable. $\overline{EA}$ must be strapped to VSS in order to enable the device to fetch code from external Program Memory.

XTAL1: Input to the inverting oscillator amplifier.

XTAL2: Output from the inverting oscillator amplifier.

OSCILLATOR CHARACTERISTICS

XTAL1 and XTAL2 are the input and output, respectively, of an inverting amplifier which can be configured for use as an on-chip oscillator, as shown in Figure 3. Either a quartz crystal or ceramic resonator may be used. More detailed information concerning the use of the on-chip oscillator is available in Application Note AP-155, ''Oscillators for Microcontrollers.''

To drive the device from an external clock source, XTAL1 should be driven, while XTAL2 floats, as shown in Figure 4. There are no requirements on the duty cycle of the external clock signal, since the input to the internal clocking circuitry is through a divide-by-two flip-flop, but minimum and maximum high and low times specified on the data sheet must be observed.

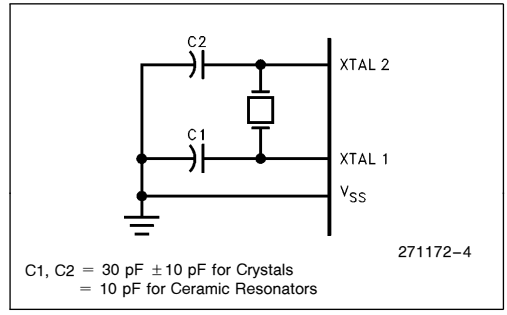


Figure 3. Oscillator Connections

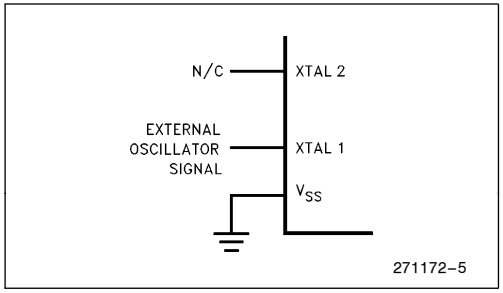


Figure 4. External Clock Drive Configuration

IDLE MODE

The user's software can invoke the Idle Mode. When the microcontroller is in this mode, power consumption is reduced. The Special Function Registers and the onboard RAM retain their values during Idle, but the processor stops executing instructions. Idle Mode will be exited if the chip is reset or if an enabled interrupt occurs. The PCA timer/counter can optionally be left running or paused during Idle Mode.

POWER DOWN MODE

To save even more power, a Power Down Mode can be invoked by software. In this mode, the oscillator is stopped and the instruction that invoked Power Down is the last instruction executed. The on-chip RAM and Special Function Registers retain their values until the Power Down Mode is terminated.

On the M80C51FB either a hardware reset or an external interrupt can cause an exit from Power Down. Reset redefines all the SFRs but does not change the on-chip RAM. An external interrupt allows both the SFRs and on-chip RAM to retain their values.

To properly terminate Power Down the reset or external interrupt should not be executed before V_{CC} is restored to its normal operating level and must be held active long enough for the oscillator to restart and stabilize (normally less than 10 ms).

With an external interrupt, INT0 and INT1 must be enabled and configured as level-sensitive. Holding the pin low restarts the oscillator but bringing the pin back high completes the exit. Once the interrupt is serviced, the next instruction to be executed after RETI will be the one following the instruction that puts the device into Power Down.

DESIGN CONSIDERATION

When the Idle Mode is terminated by a hardware reset, the device normally resumes program execution, from where it left off, up to two machine cycles before the internal reset algorithm takes control. On-chip hardware inhibits access to internal RAM in this event, but access to the port pins is not inhibited. To eliminate the possibility of an unexpected write when Idle is terminated by reset, the instruction following the one that invokes Idle should not be one that writes to a port pin or to external memory.

ONCE MODE

The ONCE (''On-Circuit Emulation'') Mode facilitates testing and debugging of systems using the M80C51FB without the M80C51FB having to be removed from the circuit. The ONCE Mode is invoked by:

1) Pull ALE low while the device is in reset and $\overline{PSEN}$ is high;
2) Hold ALE low as RST is deactivated.

While the device is in ONCE Mode, the Port 0 pins go into a float state, and the other port pins and ALE and $\overline{PSEN}$ are weakly pulled high. The oscillator circuit remains active. While the M80C51FB is in this mode, an emulator or test CPU can be used to drive the circuit. Normal operation is restored when a normal reset is applied.

Table 1. Status of the External Pins during Idle and Power Down

Mode	Program Memory	ALE	$\overline{PSEN}$	PORT0	PORT1	PORT2	PORT3
Idle	External	1	1	Float	Data	Address	Data
Power Down	External	0	0	Float	Data	Data	Data

NOTE:
For more detailed information on the reduced power modes refer to current 8-Bit Embedded Controller Handbook, and Application Note AP-255, ''Designing with the M80C51BH.''

ABSOLUTE MAXIMUM RATINGS*

Case Temperature under Bias(6) . . . . . −55°C to +125°C

Storage Temperature . . . . . −65°C to +150°C

Voltage on $\overline{EA}$/V_{PP} Pin to V_{SS} . . . . . 0V to +13.0V

Voltage on Any Other Pin to V_{SS} . . −0.5V to +6.5V

Maximum I_{OL} Per I/O Pin . . . . . 15 mA

Power Dissipation . . . . . 1.5W (based on PACKAGE heat transfer limitations, not device power consumption)

NOTICE: This is a production data sheet. The specifications are subject to change without notice.

**WARNING: Stressing the device beyond the "Absolute Maximum Ratings" may cause permanent damage. These are stress ratings only. Operation beyond the "Operating Conditions" is not recommended and extended exposure beyond the "Operating Conditions" may affect device reliability.*

Operating Conditions

Symbol	Description	Min	Max	Unit
T_C	Case Temperature (Instant On)	−55	+125	°C
V_{CC}	Digital Supply Voltage	4.0	6.0	V
f_{OSC}	Oscillator Frequency	3.5	16	MHz

D.C. CHARACTERISTICS: (Over Specified Operating Conditions)

Symbol	Parameter	Min	Max	Unit	Test Conditions
V_{IL}	Input Low Voltage	−0.5	0.2 V_{CC} − 0.1	V	
V_{IH}	Input High Voltage (Except XTAL1, RST)	0.2 V_{CC} + 0.9	V_{CC} + 0.5	V	
V_{IH1}	Input High Voltage (XTAL1, RST)	0.7 V_{CC}	V_{CC} + 0.5	V	
V_{OL}	Output Low Voltage(5) (Ports 1, 2, and 3)		0.3	V	I_{OL} = 100 μA (Note 1)
			0.45	V	I_{OL} = 1.6 mA (Note 1)
			1.0	V	I_{OL} = 3.5 mA (Notes 1, 4)
V_{OL1}	Output Low Voltage(5) (Port 0, ALE, $\overline{PSEN}$)		0.3	V	I_{OL} = 200 μA (Note 1)
			0.45	V	I_{OL} = 3.2 mA (Note 1)
			1.0	V	I_{OL} = 7.0 mA (Note 1, 4)
V_{OH}	Output High Voltage (Ports 1, 2, and 3)	V_{CC} − 0.3		V	I_{OH} = −10 μA
		V_{CC} − 0.7		V	I_{OH} = −30 μA
		V_{CC} − 1.5		V	I_{OH} = −60 μA

D.C. CHARACTERISTICS: (Over Specified Operating Conditions) (Continued)

Symbol	Parameter	Min	Max	Unit	Test Conditions
V_{OH1}	Output High Voltage (Port 0 in External Bus Mode, ALE, $\overline{PSEN}$)	$V_{CC}-0.3$		V	$I_{OH} = -200\ \mu A$ (Note 2)
		$V_{CC}-0.7$		V	$I_{OH} = -3.2$ mA
		$V_{CC}-1.5$		V	$I_{OH} = -7.0$ mA (Note 4)
I_{IL}	Logical 0 Input Current (Ports 1, 2, and 3)		−75	μA	$V_{IN} = 0.45V$
I_{LI}	Input leakage Current (Port 0)		±10	μA	$0.45V < V_{IN} < V_{CC}$
I_{TL}	Logical 1 to 0 Transition Current (Ports 1, 2, and 3)		−750	μA	$V_{IN} = 2V$
RRST	RST Pulldown Resistor	40	225	KΩ	
CIO	Pin Capacitance		10	pF	@1 MHz, 25°C
I_{CC}	Power Supply Current: Active Mode @ 16 MHz Idle Mode @ 16 MHz Power Down Mode @ 16 MHz		 45 15 130	 mA mA μA	(Note 3)

NOTES:
1. Capacitive loading on Ports 0 and 2 may cause spurious noise pulses to be superimposed on the V_{OL}s of ALE and Ports 1 and 3. The noise is due to external bus capacitance discharging into the Port 0 and Port 2 pins when these pins make 1 to 0 transitions during bus operations. In applications where capacitance loading exceeds 100 pFs, the noise pulse on the ALE signal may exceed 0.8V. In these cases, it may be desirable to qualify ALE with a Schmitt Trigger, or use an Address Latch with a Schmitt Trigger Strobe input.
2. Capacitive loading on Ports 0 and 2 cause the V_{OH} on ALE and $\overline{PSEN}$ to drop below the $V_{CC} - 0.3$ specification when the address lines are stabilizing.
3. See Figures 5–8 for load circuits. Minimum V_{CC} for Power Down is 2V.
4. Care must be taken not to exceed the maximum allowable power dissipation.
5. Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
   Maximum I_{OL} per port pin: 10mA
   Maximum I_{OL} per 8-bit port—
   Port 0: 26 mA
   Ports 1, 2 and 3: 15 mA
   Maximum total I_{OL} for all output pins: 71 mA

If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.

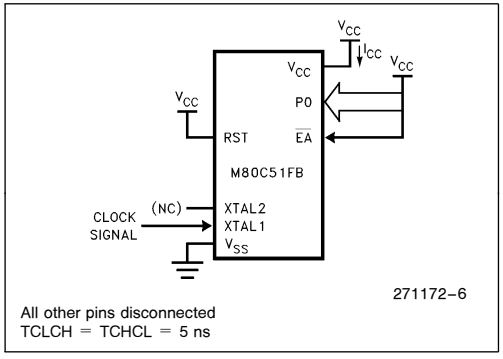


Figure 5. I_{CC} Load Circuit Active Mode

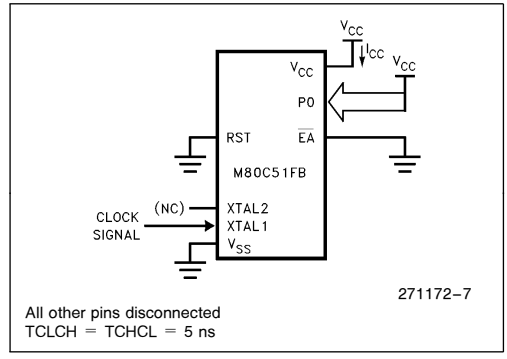


Figure 6. I_{CC} Load Circuit Idle Mode

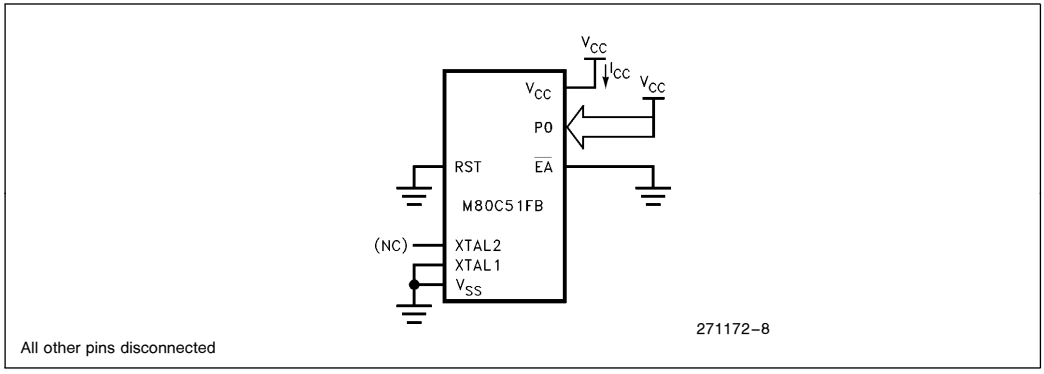


Figure 7. I_{CC} Load Circuit Power Down Mode. V_{CC} = 2.0V to 5.5V.

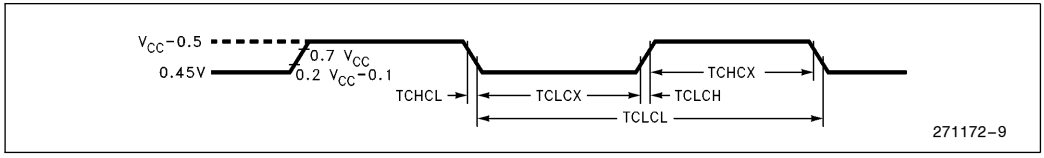


Figure 8. Clock Signal Waveform for I_{CC} Tests in Active and Idle Modes. TCLCH = TCHCL = 5 ns.

EXPLANATION OF THE AC SYMBOLS

Each timing symbol has 5 characters. The first character is always a 'T' (stands for time). The other characters, depending on their positions, stand for the name of a signal or the logical status of that signal. The following is a list of all the characters and what they stand for.

A: Address
C: Clock
D: Input Data
H: Logic level HIGH
I: Instruction (program memory contents)
L: Logic level LOW, or ALE
P: $\overline{\text{PSEN}}$
Q: Output Data
R: $\overline{\text{RD}}$ signal
T: Time
V: Valid
W: $\overline{\text{WR}}$ signal
X: No longer a valid logic level
Z: Float

For example,

TAVLL = Time from Address Valid to ALE Low
TLLPL = Time from ALE Low to $\overline{\text{PSEN}}$ Low

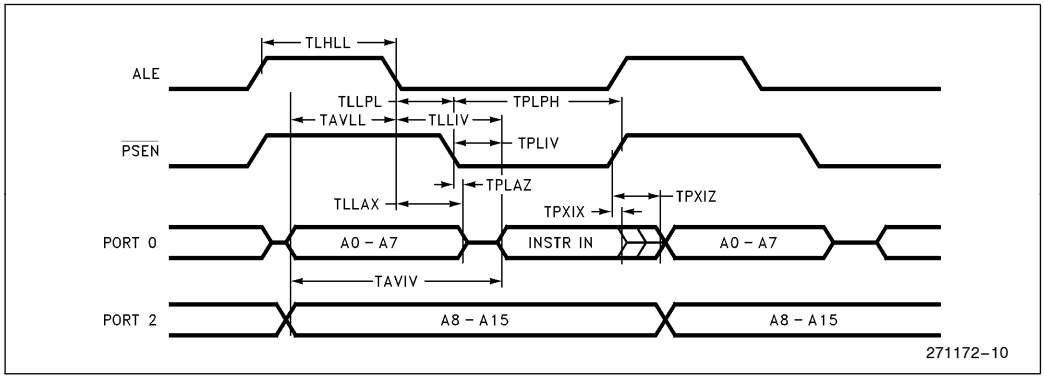
A.C. CHARACTERISTICS (Over Specified Operating Conditions)

EXTERNAL PROGRAM MEMORY CHARACTERISTICS

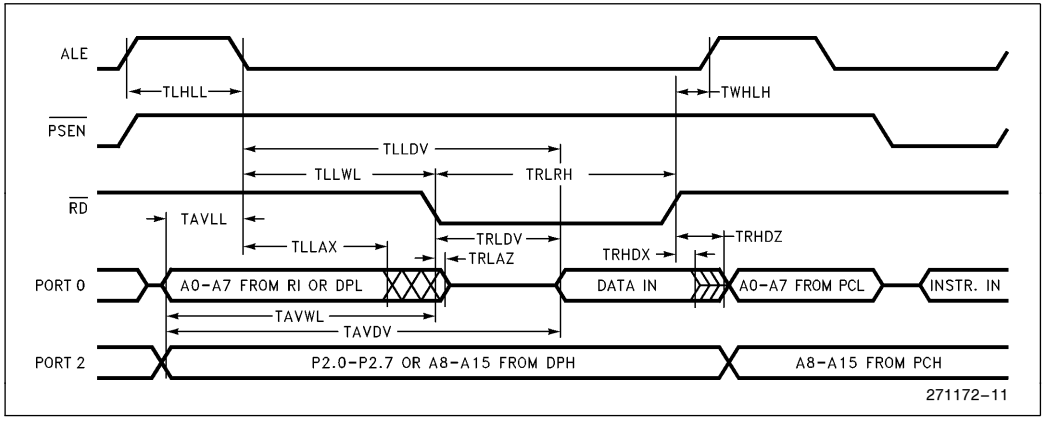
Symbol	Parameter	12 MHz Oscillator		16 MHz Oscillator		Variable Oscillator		Unit
		Min	Max	Min	Max	Min	Max	
1/TCLCL	Oscillator Frequency M80C51FB M80C51FB-16					 3.5 3.5	 12 16	MHz
TLHLL	ALE Pulse Width	127		85		2TCLCL−40		ns
TAVLL	Address Valid to ALE Low	43		23		TCLCL−40		ns
TLLAX	Address Hold After ALE Low	53		33		TCLCL−30		ns
TLLIV	ALE Low to Valid Instruction In		234		150		4TCLCL−110	ns
TLLPL	ALE Low to $\overline{PSEN}$ Low	53		33		TCLCL−30		ns
TPLPH	$\overline{PSEN}$ Pulse Width	205		143		3TCLCL−45		ns
TPLIV	$\overline{PSEN}$ Low to Valid Instruction In		145		83		3TCLCL−115	ns
TPXIX	Input Instruction Hold After $\overline{PSEN}$	0		0		0		ns
TPXIZ	Input Instruction Float After $\overline{PSEN}$		59		38		TCLCL−25	ns
TAVIV	Address to Valid Instruction In		312		208		5TCLCL−115	ns
TPLAZ	$\overline{PSEN}$ Low to Address Float		10		10		20	ns
TRLRH	$\overline{RD}$ Pulse Width	400		275		6TCLCL−100		ns
TWLWH	$\overline{WR}$ Pulse Width	400		275		6TCLCL−100		ns
TRLDV	$\overline{RD}$ Low to Valid Data In		252		147.5		5TCLCL−175	ns
TRHDX	Data Hold After $\overline{RD}$	0		0		0		ns
TRHDZ	Data Float After $\overline{RD}$		107		65		2TCLCL−60	ns
TLLDV	ALE Low to Valid Data In		517		350		8TCLCL−160	ns
TAVDV	Address to Valid Data In		585		398		9TCLCL−175	ns
TLLWL	ALE Low to $\overline{RD}$ or $\overline{WR}$ Low	200	300	138	238	3TCLCL−50	3TCLCL+50	ns
TAVWL	Address Valid to $\overline{WR}$ Low	203		120		4TCLCL−130		ns
TQVWX	Data Valid before $\overline{WR}$	33		13		TCLCL−50		ns
TWHQX	Data Hold after $\overline{WR}$	33		13		TCLCL−50		ns
TQVWH	Data Valid to $\overline{WR}$ High	433		288		7TCLCL−150		ns
TRLAZ	$\overline{RD}$ Low to Address Float		0		0		0	ns
TWHLH	$\overline{RD}$ or $\overline{WR}$ High to ALE High	43	123	23	103	TCLCL−40	TCLCL+40	ns

NOTE:
7. Case temperatures are ''instant on''.

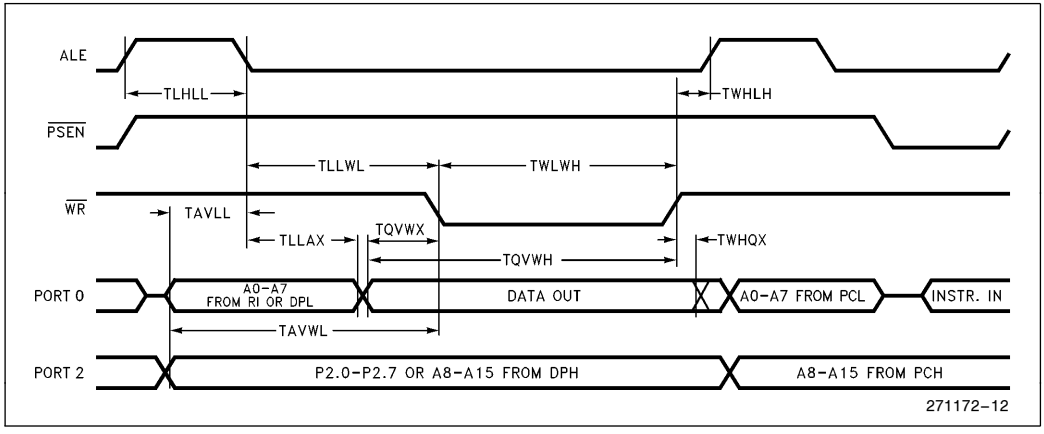
EXTERNAL PROGRAM MEMORY READ CYCLE



EXTERNAL DATA MEMORY READ CYCLE



EXTERNAL DATA MEMORY WRITE CYCLE

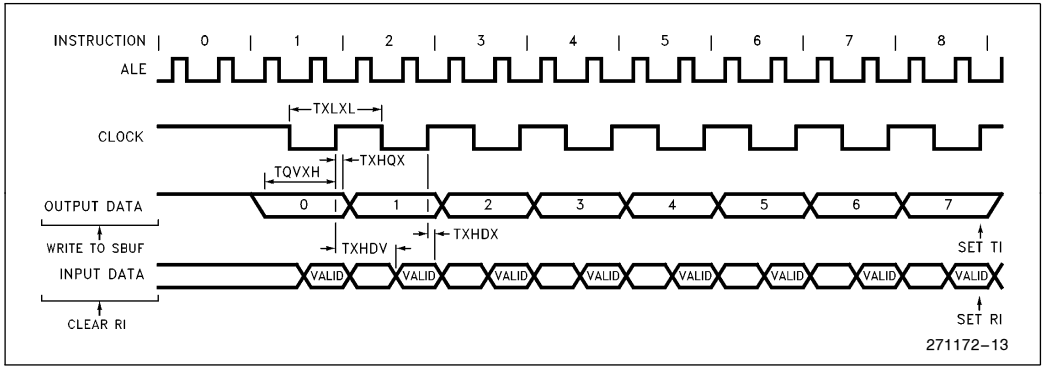


SERIAL PORT TIMING - SHIFT REGISTER MODE

Test Conditions: (Over Specified Operating Conditions)

Symbol	Parameter	12 MHz Oscillator		16 MHz Oscillator		Variable Oscillator		Units
		Min	Max	Min	Max	Min	Max	
TXLXL	Serial Port Clock Cycle Time	1		0.75		12TCLCL		μs
TQVXH	Output Data Setup to Clock Rising Edge	700		492		10TCLCL − 133		ns
TXHQX	Output Data Hold after Clock Rising Edge	50		8		2TCLCL − 117		ns
TXHDX	Input Data Hold After Clock Rising Edge	0		0		0		ns
TXHDV	Clock Rising Edge to Input Data Valid		700		492		10TCLCL − 133	ns

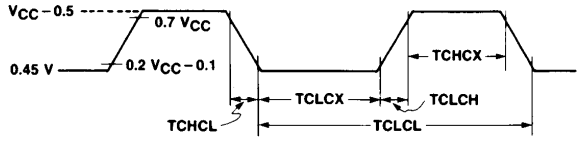
SHIFT REGISTER MODE TIMING WAVEFORMS



EXTERNAL CLOCK DRIVE

Symbol	Parameter	Min	Max	Units
1/TCLCL	Oscillator Frequency M80C51FB M80C51FB-16	 3.5 3.5	 12 16	MHz
TCHCX	High Time	20		ns
TCLCX	Low Time	20		ns
TCLCH	Rise Time		20	ns
TCHCL	Fall Time		20	ns

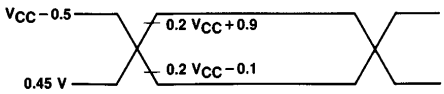
EXTERNAL CLOCK DRIVE WAVEFORM



271172–14

A.C. TESTING INPUT

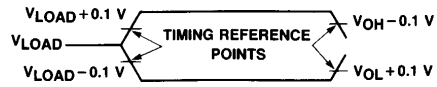
Input, Output Waveforms



271172–15

AC Inputs during testing are driven at $V_{CC} - 0.5V$ for a Logic "1" and 0.45V for a Logic "0". Timing measurements are made at V_{IH} min for a Logic "1" and V_{IL} max for a Logic "0".

Float Waveforms



271172–16

For timing purposes a port pin is no longer floating when a 100 mV change from load voltage occurs, and begins to float when a 100 mV change from the loaded V_{OH}/V_{OL} level occurs. $I_{OL}/I_{OH} \geq \pm 20$ mA.